Contact Name Title - Contact Product-Env-Stewards Authorized Representative* Product-Env-Stewards Product Enviro Compliance Title - Representative Phone - Contact* Phone - Contact* Product-Env-Stewards@onsemi.com Phone - Representative* Email - Representative* Email - Representative* Product-Env-Stewards Product-Env-Stewards@onsemi.com Requester Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM U	ASSOCIATION CONNECTIN	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
Company name* Company name* Company unique ID Unique ID Authority Response Date* 2024-05-18 Contact Name Title - Contact Phone - Contact* Product-Env-Stewards Product-Env-Stewards Authorized Representative* Title - Representative Title - Representative Title - Representative Product-Env-Stewards Outhorized Product-Env-Stewards Product-Env-Stewards Product-Env-Stewards Outhorized Product-Env-Stewards Outhorized Product-Env-Stewards Outhorized Product-Env-Stewards Outhorized Product-Env-Stewards Outhorized Product-Env-Stewards Outhorized Outhorize	752-21.1										Homogeneous Materia	als and Mfg	Informat	ion	
Semilar Contact Name Title - Contact Phone - Contact* Phone - Contact* Email - Contact* Product Envisor Compliance NA Product Envisor Stewards Produ	upplier Inforn	nation								·					
Title - Contact Name Product Env-Stewards Product Env-Stewards Product Enviro Compliance NA Product Env-Stewards Product Env-	Company name* Company unique ID					Unique ID Authority				Response Date*					
Product Env-Stewards Authorized Representative* Title - Representative Product Enviro Compliance Product Enviro Compliance NA Product Env-Stewards @onsemi.com NA Na Useful ** Na Nanufacturing Site ** Na Nanufacturing Site ** Neight* UOM U Nanufacturing Proccess Information Na Nanufacturing Product Enviro Compliance NA Na Nanufacturing Site **	nsemi											2024-05-1	.8		
Authorized Representative* Product-Env-Stewards Requester Item Number Mfr Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM U Annufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Matte Tin (Sn) - annealed CU Alloy Title - Representative Phone - Representative* NA Product-Env-Stewards@onsemi.com Manufacturing Site Weight* UOM U 2024-05-18 PANJITFG 310.0 mg Email - Representative* Weight* UOM U Manufacturing Site Weight* UoM U Manufacturing Proccess Information Ferminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3	ontact Name			Title - Contact			F	Phone - Contact*				Email - Contact*			
Product Envi-Stewards Requester Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM U Annufacturing Process Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Matte Tin (Sn) - annealed CU Alloy Terminal Plating / Grid Array Material Terminal Base Alloy Terminal B	Product-Env-Stewa	ards		Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com			
Requester Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM U DF10S2 BR SDIP PN 2A 1000V 2024-05-18 PANJITFG 310.0 mg Ex Manufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3	uthorized Represe	entative*	Title - Representative			F	Phone - Representative*				Email - Representative*				
DF10S2 BR SDIP PN 2A 1000V 2024-05-18 PANJITFG 310.0 mg Example 2024-05-18 PANJITFG 3	Product-Env-Stewa	ards		Product Enviro Compliance]	NA				Product-Env-Stewards@onsemi.com			
Anufacturing Proccess Information Terminal Plating / Grid Array Material Matte Tin (Sn) - annealed CU Alloy Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles 260 Seconds Terminal Base Alloy Deak Process Body Temperature Peak Process Body Temperature Peak Temperature Number of Reflow Cycles Seconds Terminal Plating / Grid Array Material Peak Process Body Temperature Peak	Requesto	er Item Number	Mfr Item Number		Mfr Item Name			Effective Date	Version	Manufacturing Site		W	eight*	UOM	Unit Type
Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles 260 Comments			DF10S2		BR SDIP PN 2A 10	000V		2024-05-18		P	ANJITFG	31	0.0	mg	Each
Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3 comments				arminal Raca	Alloy	STD 020 MSI	Pating	Dank Proce	ass Rody Ta	mparatur	a May Time at Peak	Temperatu	ra Numb	per of Paflow Cya	lac
omments					Alloy J-S	31D-020 MSL	Kating			•				ber of Reflow Cyc	ies
	•	ii (Sii) - aimealeu	C	U Alloy	1			400		<u> </u>	30	second	5 3		
ver 1 - maximum ume at peak temperature during soldering is 10-50 seconds		time at neak temperature	duning cal	doring is 10-2	10 seconds										
or more information regarding material composition please refer to page 3															

RoHS Material Composition Declaration			Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		by mass (100 PPM) in homogeneous material for tum (Cr6+), Polybrominated Biphenyls (PBB), Polyl Disobutyl phthalate (DIBP).							
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, admium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not ndependently verified information provided by others, Supplier agrees that, at a minimum, its provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the vertification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of hat agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.									
RoHS Declaration * 4 - Item(s	s) does not contain RoHS restricted substance	ces per the definition above except for selected exer	nptions Supplier Acceptance	* Accepted					
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead). Exemption: 7c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.									
Exemption List Version	EL-2011/534/EU								
Declaration Signature									
Instructions: Complete all of the required in Requester) and click on Submit Form to ha		"Accepted" on the Supplier Acceptance drop-do	wn. This will display the signature area. Digital	lly sign the declaration (if required by the					
Supplier Digital Signature R		,							

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	3.6	mg	Supplier	Silicon (Si)	7440-21-3		3.3768	mg
			В	Nickel (Ni)	7440-02-0		0.0324	mg
			Supplier	Gold (Au)	7440-57-5		0.018	mg
			A	Lead Oxide (PbO)	1317-36-8	7c	0.1728	mg
Die Attach Solder	2.595	mg	Supplier	Silver (Ag)	7440-22-4		0.0649	mg
			A	Lead (Pb)	7439-92-1	7a	2.4004	mg
			Supplier	Tin (Sn)	7440-31-5		0.1297	mg
Lead Frame	63.63	mg	Supplier	Iron (Fe)	7439-89-6		0.0764	mg
			Supplier	Copper (Cu)	7440-50-8		63.5346	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0191	mg
Mold Compound-Black	233.175	mg		Metal Hydroxide	proprietary data		8.1611	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		18.654	mg
			Supplier	Carbon Black (C)	1333-86-4		1.1659	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		186.54	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		18.654	mg
Plating	7.0	mg	Supplier	Tin (Sn)	7440-31-5		7	mg